



# Journal of Electronic Packaging

## CALL FOR PAPERS Special Issue - "A Tribute to Prof. Avram Bar-Cohen"

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### CALL FOR PAPERS

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#### Special Issue - "A Tribute to Prof. Avram Bar-Cohen"

This Special Issue of the *ASME Journal of Electronic Packaging* is dedicated to Prof. Avram Bar-Cohen, who passed away on October 10, 2020. Avi helped to pioneer the wider field of thermal management in electronics packaging and mentored over 70 graduate students at four institutions of higher education, all while serving as a prestigious member of academia, industry, and government. Papers in all disciplines of electronics thermal management are solicited here in honor of Prof. Bar-Cohen.

#### Topic Areas

Including but not limited to:

- Two-phase flow in minichannels and microchannels
- Nanoelectronic and optoelectronic thermal management
- Thermal interface materials and thermal metamaterials
- Transient thermal management of high-heat flux electronics
- Thermal management of power electronics and LEDs
- Heat sink and cold plate optimization and thermoelectric cooling
- Passive radiative cooling for thermal management
- Novel heat exchangers, including additively manufactured, polymeric, phase change material (PCM) heat exchangers

#### Publication Target Dates

Paper submission deadline: **June 15, 2021**  
Initial review completed: **August 1, 2021**  
Special Issue publication date: **December, 2021**

#### Submission Instructions

Papers should be submitted electronically to the journal at [journaltool.asme.org](http://journaltool.asme.org). If you already have an account, log in as author and select **Submit Paper** at the bottom of the page. If you do not have an account, select **Submissions** and follow the steps. In either case, at the **Paper Submittal** page, select the [ASME Journal of Electronic Packaging](#) and then select the Special Issue - "A Tribute to Prof. Avram Bar-Cohen."

Papers received after the deadline or papers not selected for inclusion in the Special Issue may be accepted for publication in a regular issue.

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